L Number	Hits	Search Text	DB	Time stamp
1	114566	photolithography or lithography	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 17:58
2	1508272	mold$3 or mould$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 17:58
3	9260	(photolithography or lithography) and (mold$3 or mould$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 17:58
4	36986	65/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 17:58
5	70	((photolithography or lithography) and (mold$3 or mould$3)) and 65/$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 17:59
7	819	fluorine and ((photolithography or lithography) and (mold$3 or mould$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 17:59
6	22	fluorine and (((photolithography or lithography) and (mold$3 or mould$3)) and 65/$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 18:00
8	1810	fluorine same (sinter$ or consolidat$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 18:00
9	20	(fluorine same (sinter$ or consolidat$)) and ((photolithography or lithography) and (mold$3 or mould$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 18:31
10	8	09/397573	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 18:30
11	107	(photolithography or lithography) and (fluorine same (sinter$ or consolidat$))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 18:31
12	20	((fluorine same (sinter$ or consolidat$)) and ((photolithography or lithography) and (mold$3 or mould$3))) and (remov$4 or etch$6 or cut$4 or abrad$5 or polish$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 18:33

C:\APPS\east\workspaces\Default EAST Workspace (Flat Panel).wsp

13	20	((fluorine same (sinter$ or consolidat$)) and ((photolithography or lithography) and (mold$3 or mould$3))) and (remov$4 or etch$6 or cut$4 or abrad$5 or polish$3) and surface	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 18:33
14	20	((fluorine same (sinter$ or consolidat$)) and ((photolithography or lithography) and (mold$3 or mould$3))) and (remov$4 or etch$6 or cut$4 or abrad$5 or polish$3) and surface	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 18:44
15	8986	(photolithography or lithography) and (fluorine or siF.$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 18:45
16	238934	surface near2 (grind$4 or ground$3 or polish$4 or abrad$5 or etch$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 18:51
17	2378	((photolithography or lithography) and (fluorine or siF.$)) and (surface near2 (grind$4 or ground$3 or polish$4 or abrad$5 or etch$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 18:47
18	22	65/$.ccls. and (((photolithography or lithography) and (fluorine or siF.$)) and (surface near2 (grind$4 or ground$3 or polish$4 or abrad$5 or etch$3)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 18:47
19	266758	surface near2 (grind$4 or ground$3 or abrad$5 or remov$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 19:03
20	1656	(surface near2 (grind$4 or ground$3 or abrad$5 or remov$4)) and ((photolithography or lithography) and (fluorine or siF.$))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 18:52
21	120480	surface near2 (grind$4 or ground$3 or abrad$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 18:52
22	1656	((photolithography or lithography) and (fluorine or siF.$)) and (surface near2 (grind$4 or ground$3 or abrad$5 or remov$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 18:53
23	197	((photolithography or lithography) and (fluorine or siF.$)) and (surface near2 (grind$4 or ground$3 or abrad$5))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 19:02
24	333	(mold$3 or mould$3) and (((photolithography or lithography) and (fluorine or siF.$)) and (surface near2 (grind$4 or ground$3 or polish$4 or abrad$5 or etch$3)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 19:02
25	1	(mold$3 or mould$3) and l122	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 19:02

C:\APPS\east\workspaces\Default EAST Workspace (Flat Panel).wsp

26	258	(mold$3 or mould$3) and (((photolithography or lithography) and (fluorine or siF.$)) and (surface near2 (grind$4 or ground$3 or abrad$5 or remov$4)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 19:02
27	157999	surface near (grind$4 or ground$3 or abrad$5 or remov$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 19:03
28	11	(surface near2 (grind$4 or ground$3 or polish$4 or abrad$5 or etch$3)) near4 ingot and (photolithography or lithography)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 19:04